

MADL-011125-DIE

Rev. V1

#### **Features**

Peak Power Handling: 16 WCW Power Handling: 6.3 W

Low Insertion Loss: 0.7 dB @ 20 GHz
Flat Leakage Power: 16.5 dBm @ 18 GHz

Die size: 1.77 x 0.97 x 0.10 mm

Passive DeviceRoHS\* Compliant

## **Applications**

- Receiver Protection
- Radar Systems
- · Radio Frequency Front-End Modules

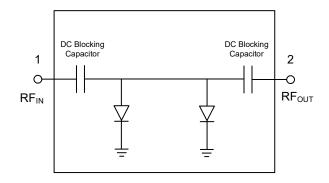
## **Description**

MADL-011125-DIE is a fully integrated diode limiter. It is a passive device, DC decoupled at both input and output RF ports.

The limiter can handle 16 W peak power with a low flat leakage of 16.5 dBm at 18 GHz.

MADL-011125-DIE is available in die form. It is ideally suited for high frequency, high peak power receiver protection.

# Functional Schematic



## **Pin Configuration**

Pin #	Function		
1	RF Input		
2	RF Output		
Backside	Ground <sup>1</sup>		

1. The entire exposed pad on the die bottom must be connected to RF, DC and thermal ground.

## **Ordering Information**

Part Number	Package		
MADL-011125-DIE	Gel-Pak		
MADL-011125-SMB	Sample Board		

<sup>\*</sup> Restrictions on Hazardous Substances, compliant to current RoHS EU directive.



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# Electrical Specifications: $T_A = +25$ °C, $Z_0 = 50 \Omega$

Parameter	Test Conditions	Units	Min.	Тур.	Max.
Insertion Loss	2 GHz 8 GHz 16 GHz 20 GHz	dB	_	0.7 0.3 0.6 0.7	_
Input & Output Return Loss	2 GHz 8 GHz 16 GHz 20 GHz	dB	_	18 18 18 18	_
CW Power Handling	_	dBm	_	38	_
CW Flat Leakage	2 GHz 10 GHz 18 GHz	dBm	_	20.5 21.0 16.5	_
CW P1dB	_	dBm	_	19	_
Pulsed Peak Power Handling	1 μs PW, 1% Duty Cycle	dBm	_	42	_
Spike Leakage Power	1 μs PW, 1% DC, 33 dBm Input 2 GHz 10 GHz 18 GHz	dBm	_	20 16 12	_
Spike Leakage Energy	1 μs PW, 1% DC, 33 dBm Input 10 GHz 18 GHz	ergs	_	1.9e-3 0.8e-3	_
1 dB Recovery Time	1 μs PW, 1% DC, 33 dBm Input	ns	_	45	_
3 dB Recovery Time	1 μs PW, 1% DC, 33 dBm Input	ns	_	35	_

# **Absolute Maximum Ratings<sup>2,3</sup>**

Parameter	Absolute Maximum		
CW Incident Power	38.5 dBm @ +85°C		
Peak Incident Power	42.4 dBm @ +85°C		
Junction Temperature <sup>6</sup>	+150°C		
Operating Temperature	-40°C to +85°C		
Storage Temperature	-55°C to +150°C		

- Exceeding any one or combination of these limits may cause permanent damage to this device.
- MACOM does not recommend sustained operation near these survivability limits.
- 4. Operating at nominal conditions with  $T_J \le +150^{\circ} C$  will ensure MTTF > 1 x  $10^6$  hours.

# **Handling Procedures**

Please observe the following precautions to avoid damage:

## **Static Sensitivity**

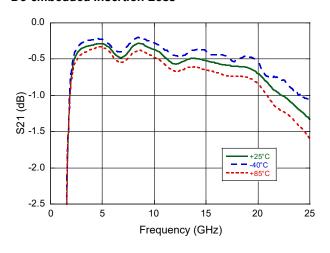
These electronic devices are sensitive to electrostatic discharge (ESD) and can be damaged by static electricity. Proper ESD control techniques should be used when handling these devices.



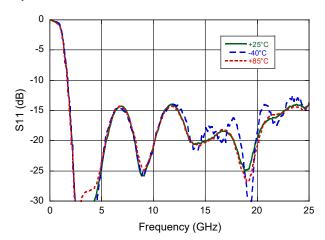
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# Typical Small-Signal Performance, Die On-Board: Over Temperature, $Z_0 = 50 \Omega$

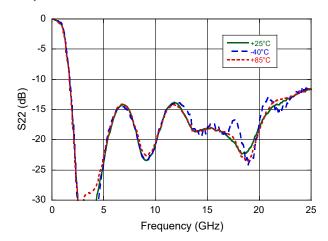
### **De-embedded Insertion Loss**



### Input Return Loss



### **Output Return Loss**

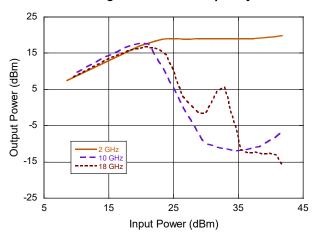




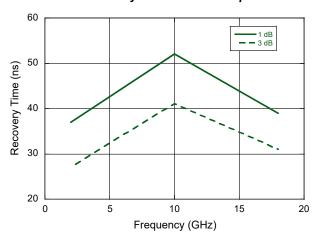
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# Typical RF Power Performance, Die On-Board: $Z_0 = 50 \Omega$ , $T_A = 25^{\circ}$ C, 1 µs Pulse Width, 1% Duty Cycle

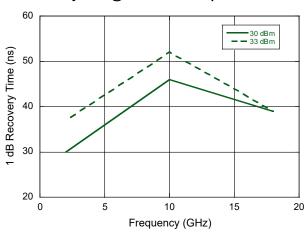
### Pulsed Flat Leakage Power over Frequency



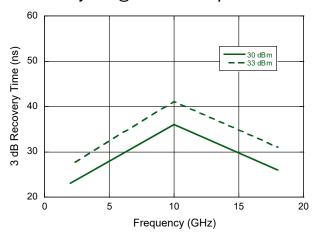
### 1dB and 3dB Recovery time at 33 dBm Input Power



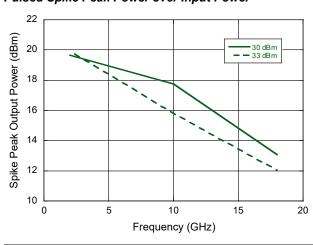
### 1dB Recovery time @ 30 & 33 dBm Input Power



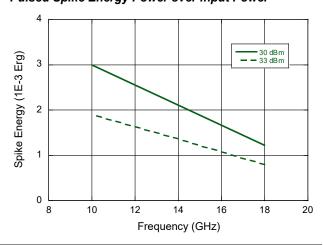
### 3dB Recovery time @ 30 & 33 dBm Input Power



### Pulsed Spike Peak Power over Input Power



### Pulsed Spike Energy Power over Input Power



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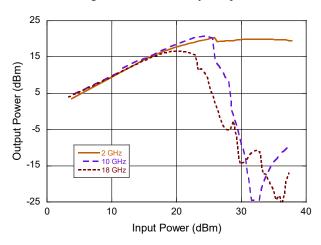
Visit <a href="https://www.macom.com">www.macom.com</a> for additional data sheets and product information.



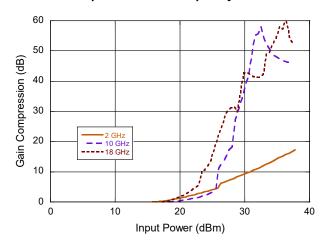
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# Typical RF Power Performance, Die On-Board: $Z_0$ = 50 $\Omega$ , $T_A$ = 25°C

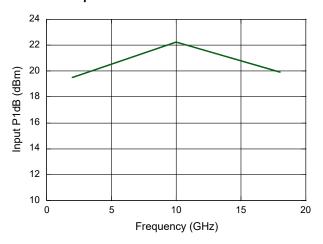
### CW Flat Leakage Power over Frequency



### CW Gain Compression over Frequency



#### CW 1dB Compression Point

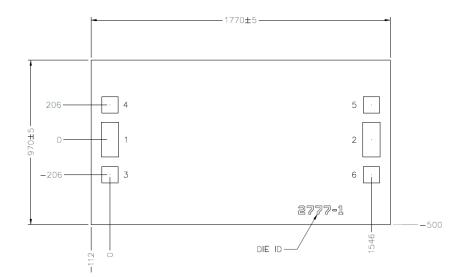




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# **Die Outline Drawing**



BOND PAD DIM. (µm)					
PAD	Χ (μm)	Υ (μm)			
1,2	104	204			
3,4,5,6	96	96			

NOTES — UNLESS OTHERWISE SPECIFIED:

1. ALL DIMENSIONS SHOWN ARE μm WITH A TOLERANCE OF ±5μm.

2. DIE THICKNESS IS 100 ±10μm

3. BOND PAD/BACKSIDE METALLIZATION: GOLD.

4. DIMENSIONS REFLECT THE FINAL SAWN DIE

# **Diode Limiter** 2 - 20 GHz



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